

Sensors and Materials
Special Issue on
Materials, Devices, Circuits, and Analytical Methods for Various Sensors (Selected Papers from ICSEVEN 2020)

Call for Papers

The era of ubiquitous sensing has begun recently thanks to the rapid development of IoT. Sensors are essential components of automotive electronic systems used in modern applications including smart industry, smart city, smart car, robot, smart building and home, and so forth. This issue will focus on all aspects of research and development related to sensor materials, sensor devices, sensor circuits, sensor readout circuits, sensor modules, sensor subsystems or systems, and analytical software, deep learning, and artificial intelligence (AI) for sensor and materials applications. Sensor technology can also be applied to the management of related innovations about data bases and network technologies in business.

We invite authors to contribute their original research as well as comprehensive review articles on the recent progress in all types of materials, devices, circuits, analytical methods, and applications related to various sensors. Potential topics include but are not limited to the following:

- sensor materials,
- sensor devices and sensor arrays/nanosensors/MEMS sensors,
- electrochemical sensors,
- microwave sensors,
- sensor applications to industry, medicine, biosignal monitoring, environmental monitoring, corrosion, and so forth,
- analytical methods, modeling, readout circuits, and software for various sensors,
- deep learning and artificial intelligence (AI) for sensor and materials applications,
- sensor technology and new sensor principles, and
- sensor technology application and innovation issues related to management.

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As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 99360 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors will bear the proofreading fee (JPY 10000–15000 for electronic proofreading), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

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